ON Semiconductor

PRODUCT BULLETIN
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03 Oct 2007

SUBJECT: ON Semiconductor Product Bulletin #16053

TITLE: Discontinuance of Dry Pack for NCP590MNxxTAG Products

PROPOSED FIRST SHIP DATE: 03 Oct 2007

AFFECTED PRODUCT DIVISION: Automotive & Power Regulation Group

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor sales office or Bett Lofts <Beatriz.Lofts@onsemi.com>

NOTIFICATION TYPE:
ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact your local ON Semiconductor sales office.

DESCRIPTION AND PURPOSE:

The temporary released of NCP590MNxxTAG devices as MSL 3 has ended. Product has shown compliance with Moisture Sensitivity Level 1 (MSL 1). Effective Oct 1, 2007, dry packing will be discontinued for following devices product will be shipped per MSL 1 packing.

AFFECTED DEVICE LIST

PART

NCP590MN5ATAG
NCP590MN5DTAG
NCP590MNOATAG
NCP590MNDPTAG
NCP590MNPPTAG